

描述 / Descriptions

SOT-89 塑封封装 NPN 半导体三极管。Silicon NPN transistor in a SOT-89 Plastic Package.

特征 / Features

饱和压降低,高速开关时间,体积小,可与 2SA1213 互补。

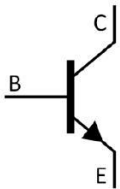
Low collector saturation voltage, High speed switching time, small flat package, Complementary to 2SA1213.

用途 / Applications

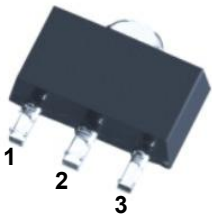
用于功率开关和放大。

Power amplifier and switching applications.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1 : Base PIN 2 : Collector PIN 3 : Emitter

印章代码 / Marking

h_{FE} Classifications Symbol	O	Y
h_{FE} Range	70~140	120~240
Marking	HMO *	HMY *

极限参数 / Absolute Maximum Ratings(Ta=25°C)

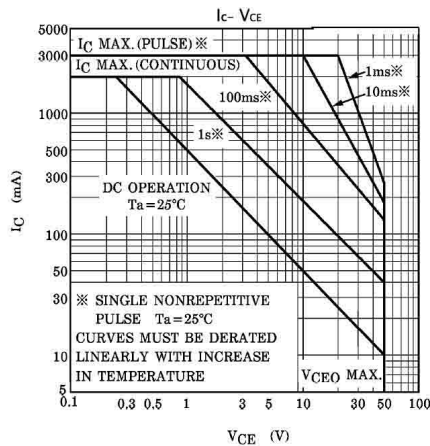
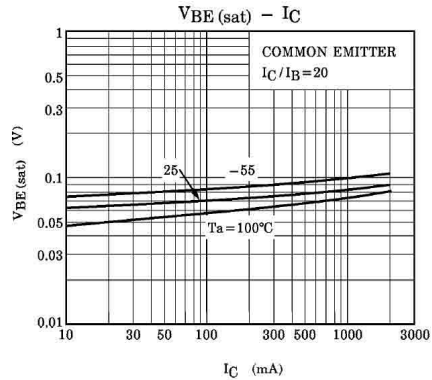
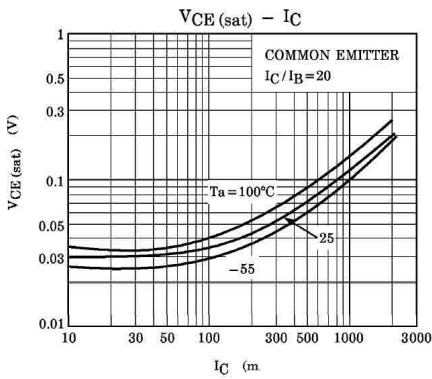
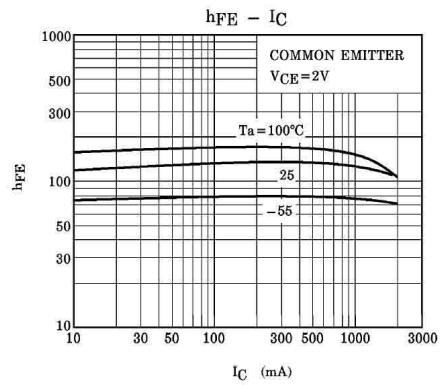
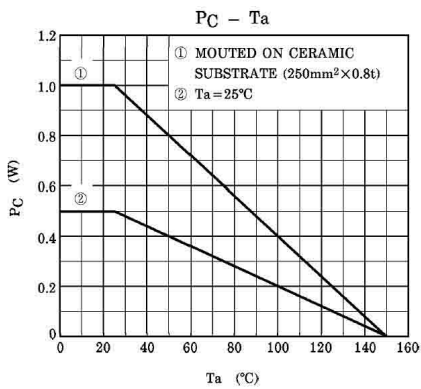
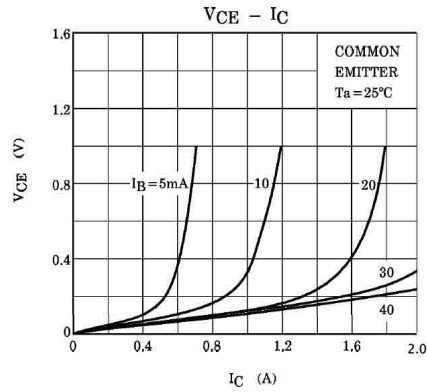
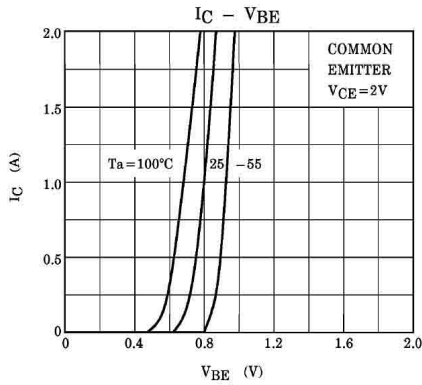
参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	V_{CBO}	50	V
Collector to Emitter Voltage	V_{CEO}	50	V
Emitter to Base Voltage	V_{EBO}	5.0	V
Collector Current-Continuous	I_C	2.0	A
Collector Base-Continuous	I_B	0.4	A
Collector Power Dissipation	P_C	500	mW
Collector Power Dissipation*	* $P_C(T_a=25^\circ\text{C})$	1000	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

*BR2SC2873 mounted on ceramic substrate(250mm²×0.8t)

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector Cut-Off Current	I_{CBO}	$V_{CB}=50V$ $I_E=0$			0.1	μA
Emitter Base Cut-Off Current	I_{EBO}	$V_{EB}=5.0V$ $I_C=0$			0.1	μA
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C=10mA$ $I_B=0$	50			V
DC Current Gain	$h_{FE(1)}$	$V_{CE}=2.0V$ $I_C=500mA$	70		240	
	$h_{FE(2)}$	$V_{CE}=2.0V$ $I_C=2.0A$	20			
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=1.0A$ $I_B=0.05A$			0.5	V
Emitter to Base Saturation Voltage	V_{BE}	$I_C=1.0A$ $I_B=0.05A$			1.2	V
Transition Frequency	f_T	$V_{CE}=2.0V$ $I_C=500mA$		120		MHz
Collector Output Capacitance	C_{ob}	$V_{CB}=10V$ $I_E=0$ $f=1MHz$		30		pF
Turn-OnTime	t_{on}	$V_{CC}=30V$ $I_{B1}=-I_{B2}=0.05A$		0.1		μS
Storage Time	t_{stg}			1.0		μS
Fall Time	t_f			0.1		μS

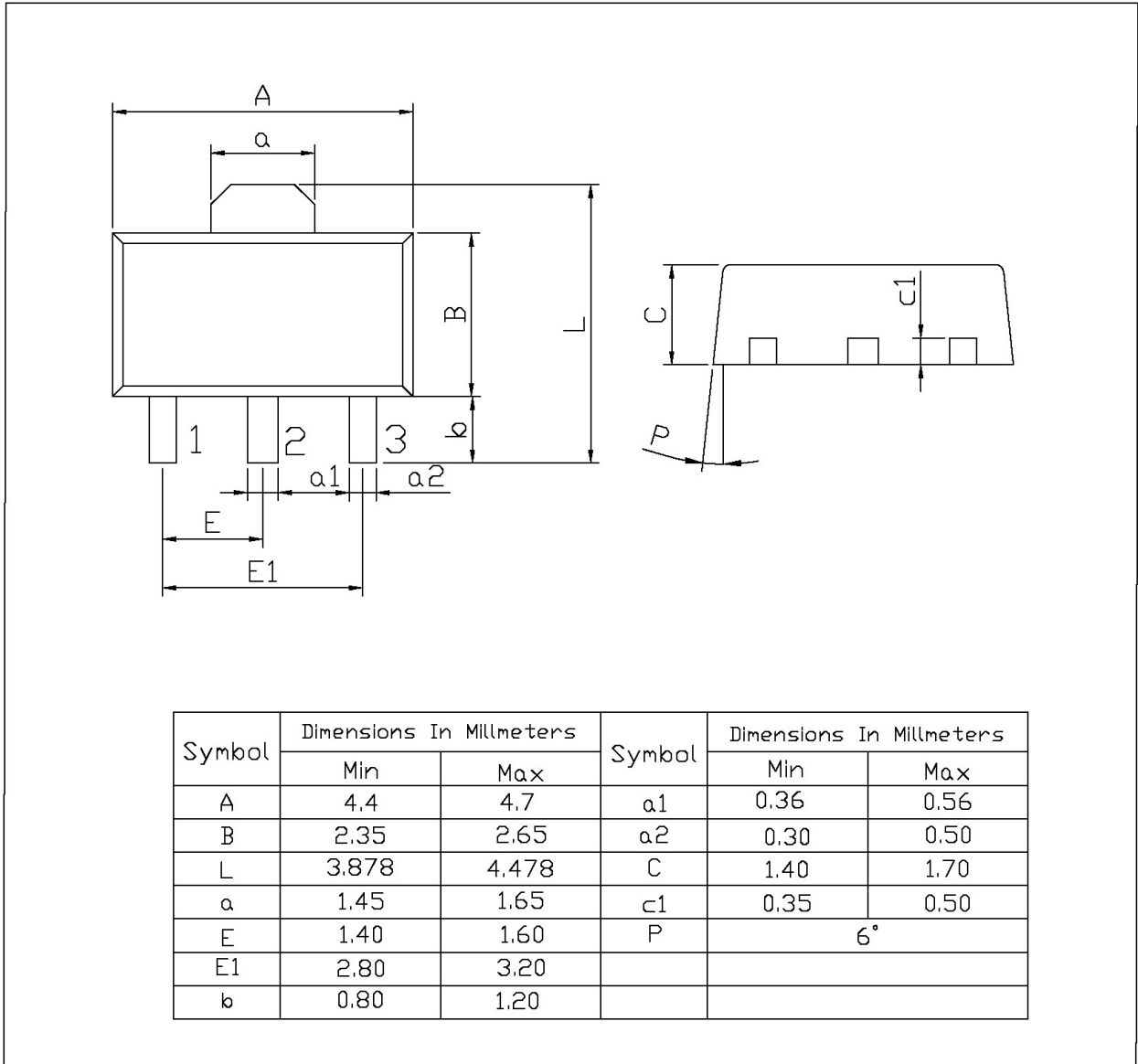
电参数曲线图 / Electrical Characteristic Curve



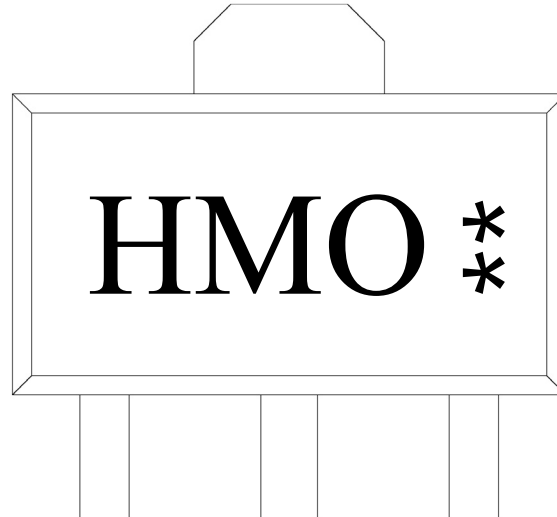
外形尺寸图 / Package Dimensions

SOT-89

单位: mm



印章说明 / Marking Instructions



说明：

- H： 为公司代码
- M： 为型号代码
- O： 为档次代码
- **： 为生产批号代码，随生产批号变化。

Note:

- H: Company Code.
- M: Product Type.
- O: h_{FE} Classifications Symbol
- ** : Lot No. Code, code change with Lot No.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25~150°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C 时间：10±1 sec.

Temp.:260±5°C Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-89	1,000	7	7,000	8	56,000	7" x12	180×120×180	385×257×392

使用说明 / Notices